AMENDMENTS TO THE CLAIMS

1. (currently amended) A micro-shape transcription method comprising:

preparing a mold having a transcription face on which a concavo-convex pattern is formed,

pressing the transcription face against a base material softened by heating,

then forcibly separating the mold from the base material to transcribe a reverse pattern of the concavo-convex pattern to the surface of the base material,

wherein the sectional form of the concavo-convex pattern is rectangular,

wherein when assuming a temperature for pressing the mold against the base material as T_1 (°C), a temperature for separating the mold from the base material as T_2 (°C), thermal expansion coefficients of the mold and the base material as α_a and α_b , and the maximum distance between the transcription center of the transcription face and the concavo-convex pattern as d (mm), the timing of the forcible separation of the mold from the base material is determined so that the following relations (1), and (2), and (3):

$$T_1 \ge T_2 \qquad \dots (1)$$

$$|\alpha_a - \alpha_b| \cdot (T_1 - T_2) \cdot d \le 4 \times 10^{-2}$$
 ...(2)

$$|\alpha_{\rm e} - \alpha_{\rm b}| \ge 50 \times 10^{-7} / {\rm °C}$$
 ...(3)

are simultaneously satisfied.

- 2. (original) The micro-shape transcription method according to claim 1, wherein the transcription face of the mold is a plane or stepped plane.
- 3. (canceled)

- 4. (canceled)
- 5. (original) The micro-shape transcription method according to claim 1 or 2, wherein the concavo-convex pattern has a line width of $100 \mu m$ or less.
- 6. (original) The micro-shape transcription method according to claim 1 or 2, wherein the concavo-convex pattern has a depth of 1 μ m or more.
- 7. (original) The micro-shape transcription method according to claim 1 or 2, wherein the base material uses an optically-transparent thermoplastic resin or glass.
- 8. (original) The micro-shape transcription method according to claim 7, wherein the thermoplastic resin is selected from the group consisting of polyolefin-, polymethyl-methacrylate-, polycarbonate-, norbornane-, and acrylic-based resins.
- 9. (currently amended) A micro-shape transcription apparatus comprising:
- a first mold means provided with a transcription face having a micro-shape that is rectangular in cross section;
- a second mold means facing the first mold means and holding a base material thereon;
- a mechanism for driving at least one of the first and second mold means to forcibly separate the first mold means from the base material;

a heating source for controlling temperatures of the first and second mold means such that when a temperature for pressing the transcription face against the base material is T_1 (°C), a temperature for separating the transcription face from the base material is T_2 (°C), thermal expansion coefficients of the transcription face and the base material are α_a and α_b , and a maximum distance between a transcription center of the transcription face and a concavo-convex pattern is d (mm), wherein the mechanism drives said first mold means when the following relations (1), and (2), and (3):

$$T_1 \ge T_2 \qquad \dots (1)$$

$$|\alpha_a - \alpha_b| \cdot (T_1 - T_2) \cdot d \le 4 \times 10^{-2}$$
 ...(2)

$$|\alpha_a - \alpha_b| \ge 50 \times 10^{-7} / ^{\circ} \text{C}$$
 ...(3)

are simultaneously satisfied; and

a vacuum chuck for attracting and fixing the base material to the second mold means.

- 10. (original) An optical-component manufacturing method wherein a pattern for controlling light of an optical component is formed in accordance with the micro-shape transcription method of claim 1 or 2.
- 11. (original) An optical waveguide manufacturing method wherein a pattern corresponding to a core of an optical component is formed in accordance with the microshape transcription method of claim 1 or 2.

- 12. (previously presented) The micro-shape transcription method of claim 1, wherein T₁ is up to 180°C.
- 13. (previously presented) The micro-shape transcription method of claim 1, wherein T₂ is 150°C.
- 14. (previously presented) The micro-shape transcription method of claim 1, wherein T₁ is 160°C and T₂ ranges from 100-140°C.
- 15. (previously presented) The micro-shape transcription method of claim 1, wherein T_1 is 180° C and T_2 ranges from $100\text{-}150^{\circ}$ C.
- 16. (previously presented) The micro-shape transcription apparatus according to claim 9, wherein T₁ is 160°C and T₂ ranges from 100-140°C.
- 17. (previously presented) The micro-shape transcription apparatus according to claim 9, wherein T₁ is 180° C and T₂ ranges from 100-150° C.
- 18. (currently amended) A mold for a micro-shape transcription apparatus that molds a base material having a thermal expansive coefficient of α_b at a temperature T_1 and that separates said mold from the base material while the base material is at a temperature T_2 where $T_1 \geq T_2$, said mold comprising:
 - a transcription face having a thermal expansion coefficient of α_a , and

said transcription face having a maximum distance d between a transcription center of the transcription face and a concavo-convex pattern of the transcription face is rectangular in cross section,

wherein
$$|\alpha_a - \alpha_b| \ge 50 \text{ x } 10^{-7}/^{\circ}\text{C}$$
, and

wherein
$$|\alpha_a - \alpha_b| \cdot (T_1 - T_2) \cdot d \le 4 \times 10^{-2}$$
; and

wherein T₂ ranges from 100-150°C.